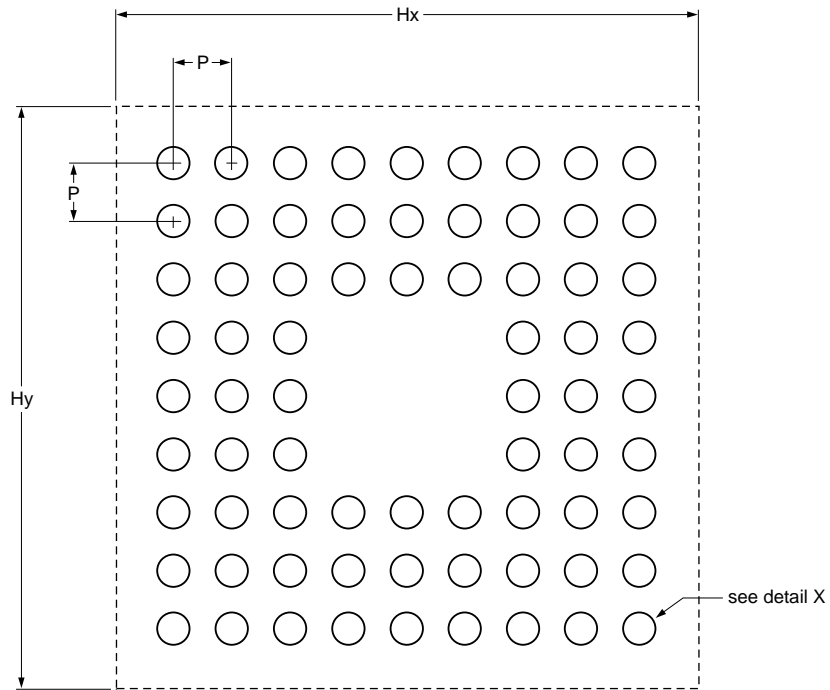





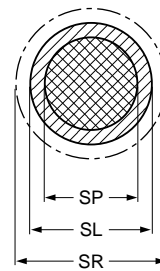
Footprint information for reflow soldering of HBGA292 package

SOT553-1



Generic footprint pattern
Refer to the package outline drawing for actual layout

-  solder land
-  solder paste deposit
-  solder land plus solder paste
- occupied area
- solder resist



detail X

DIMENSIONS in mm

P	SL	SP	SR	Hx	Hy
1.27	0.600	0.500	0.750	27.575	27.575